



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS5012-1EKB		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001109496						
<b>Package</b>		PG-DSO-14-47		<b>Weight*</b>		150.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.564	2.36	2.36	23649	23649
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		115	
	non noble metal	zinc	7440-66-6	0.069	0.05		459	
	non noble metal	iron	7439-89-6	1.383	0.92		9180	
wire	non noble metal	copper	7440-50-8	56.175	37.28	38.26	372765	382519
	non noble metal	copper	7440-50-8	0.692	0.46	0.46	4589	4589
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1112
	plastics	epoxy resin	-	7.711	5.12		51166	
	inorganic material	silicondioxide	60676-86-0	75.933	50.38	55.61	503877	556155
leadfinish	non noble metal	tin	7440-31-5	2.472	1.64	1.64	16401	16401
plating	noble metal	silver	7440-22-4	1.470	0.98	0.98	9757	9757
glue	plastics	epoxy resin	-	0.183	0.12		1213	
	noble metal	silver	7440-22-4	0.862	0.57	0.69	5717	6930
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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